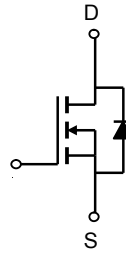
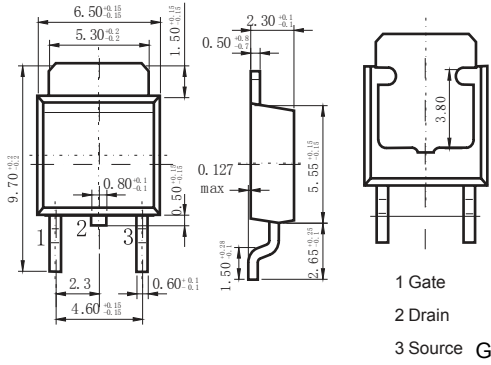


N-Channel MOSFET

TO-252

Unit: mm



■ Features

- $V_{DS} (V) = 30V$
- $I_D = 33A (V_{GS} = 10V)$
- $R_{DS(ON)} < 4.3m\Omega (V_{GS} = 10V)$
- $R_{DS(ON)} < 6.5m\Omega (V_{GS} = 4.5V)$

■ Absolute Maximum Ratings  $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	$V_{DS}$	30	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current (Note.1)	$I_D$	$T_a=25^\circ C$	33	A
		$T_c=70^\circ C$	70	
Pulsed Drain Current	$I_{DM}$	100		
Power Dissipation	$P_D$	$T_c=25^\circ C$	88	W
		$T_a=70^\circ C$	8.3	
Thermal Resistance.Junction- to-Ambient (Note.1)	$R_{thJA}$	$t \leq 10 \text{ sec}$	18	$^\circ C/W$
		Steady State	50	
Thermal Resistance.Junction- to-Case	$R_{thJC}$	1.5		
Junction Temperature	$T_J$	150	$^\circ C$	
Storage Temperature Range	$T_{stg}$	-55 to 150		

Note.1: Surface Mounted on FR4 Board,  $t \leq 10 \text{ sec}$ .

**N-Channel MOSFET**
**■ Electrical Characteristics Ta = 25°C**

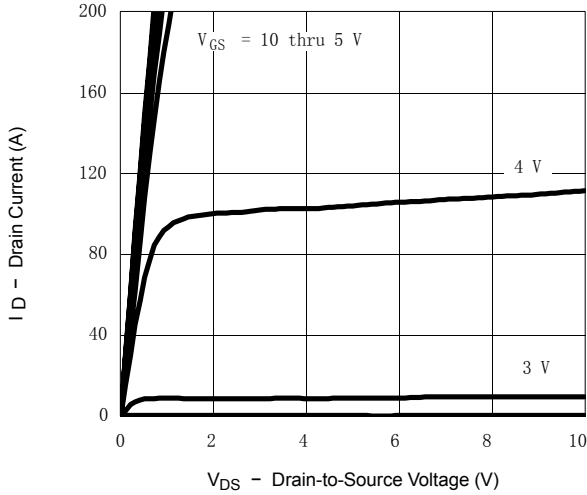
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> =250 μA, V <sub>GS</sub> =0V	30			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V			1	μA
		V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C			50	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1		3	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A		3.5	4.3	mΩ
		V <sub>GS</sub> =10V, I <sub>D</sub> =20A, T <sub>J</sub> =125°C			7	
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A		5.1	6.5	
On State Drain Current	I <sub>D(ON)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =5V	50			A
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =20A	20			S
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1MHz (Note.1)		5100		pF
Output Capacitance	C <sub>oss</sub>			860		
Reverse Transfer Capacitance	C <sub>rss</sub>			430		
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz (Note.1)	0.5	1	1.5	Ω
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =50A (Note.1)		90	135	nC
Gate Source Charge	Q <sub>gs</sub>			18		
Gate Drain Charge	Q <sub>gd</sub>			16		
Turn-On DelayTime	t <sub>d(on)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =0.3Ω, R <sub>G</sub> =2.5Ω, I <sub>D</sub> =50A (Note.1)		12	20	ns
Turn-On Rise Time	t <sub>r</sub>			12	20	
Turn-Off DelayTime	t <sub>d(off)</sub>			40	60	
Turn-Off Fall Time	t <sub>f</sub>			10	15	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =50A, di/dt=100A/μs		40	80	
Maximum Body-Diode Continuous Current	I <sub>S</sub>				8.3	A
Pulsed Current	I <sub>SM</sub>				100	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =100A, V <sub>GS</sub> =0V		1.2	1.5	V

Note.1: Pulse test; pulse width ≤ 300us, duty cycle ≤ 2%.

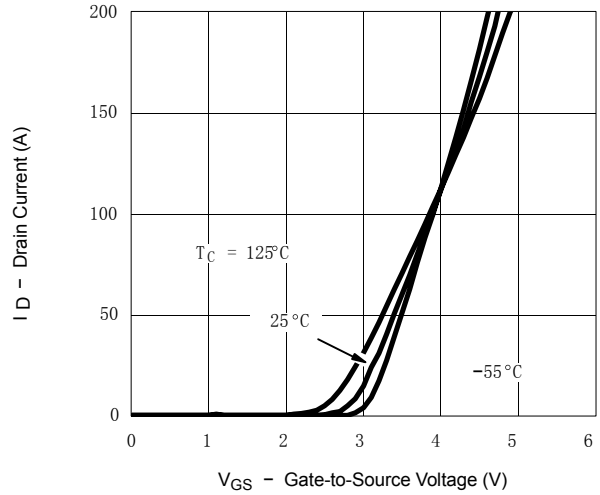
N-Channel MOSFET

Typical Characteristics

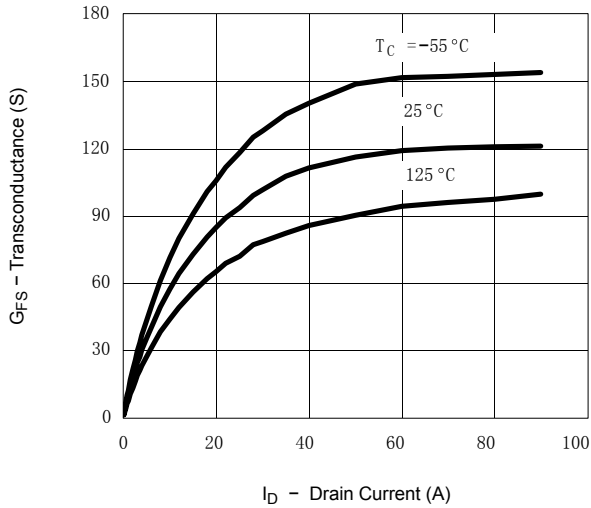
Output Characteristics



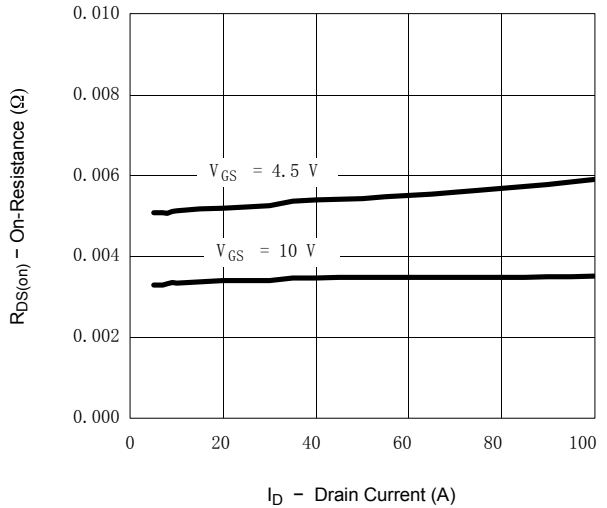
Transfer Characteristics



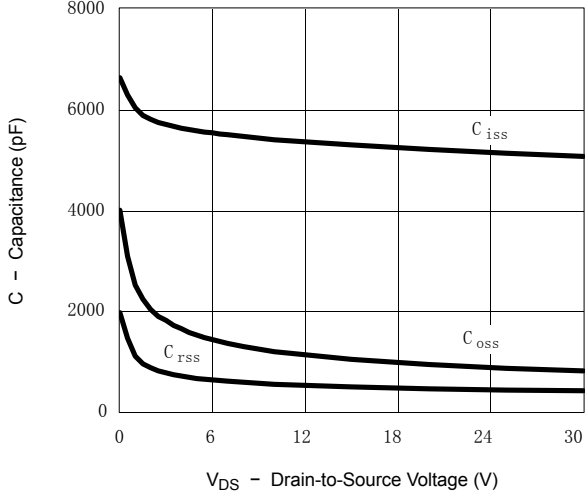
Transconductance



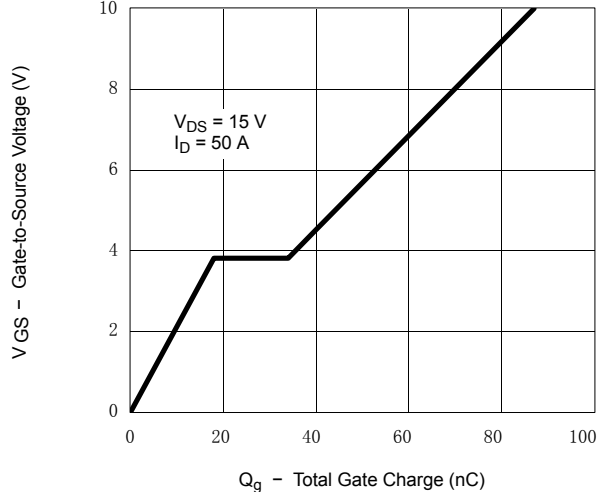
On-Resistance vs. Drain Current



Capacitance



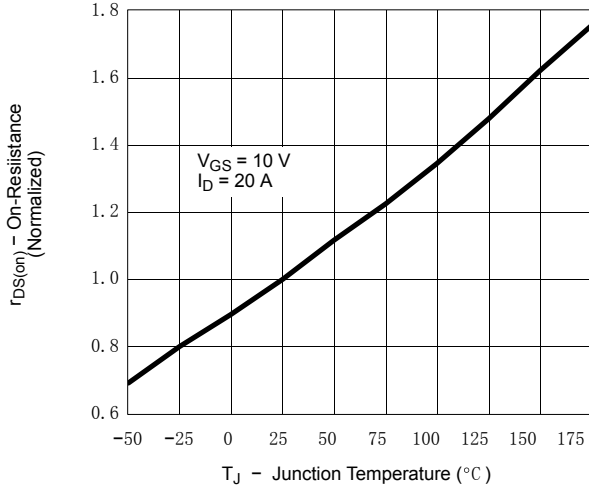
Gate Charge



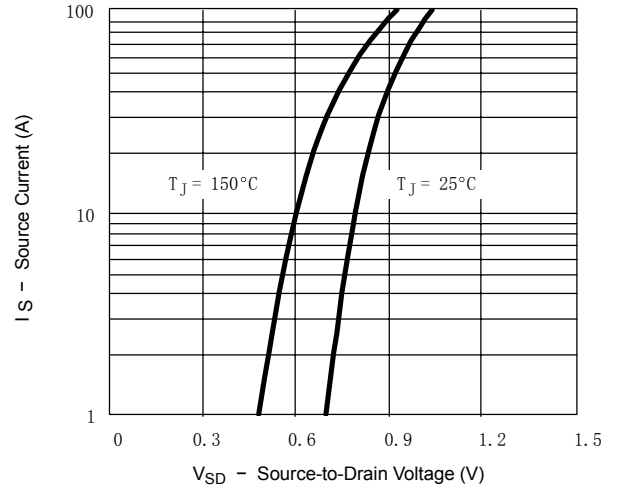
N-Channel MOSFET

Typical Characteristics

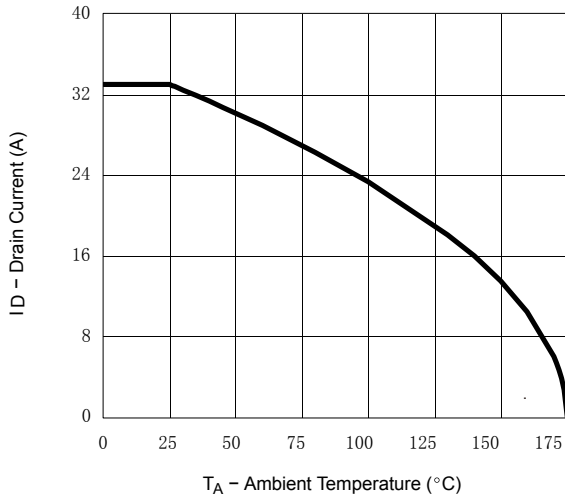
On-Resistance vs. Junction Temperature



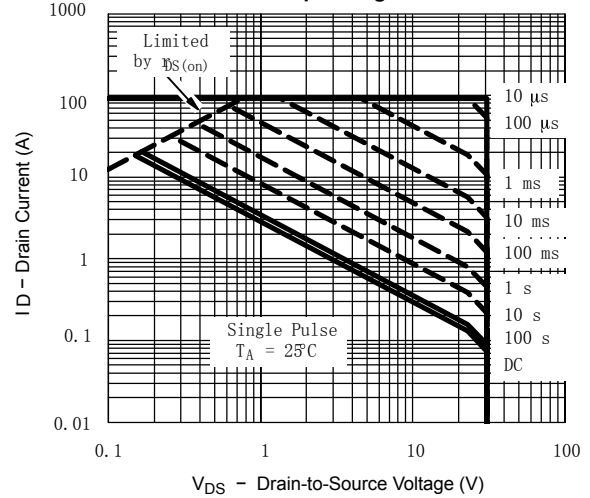
Source-Drain Diode Forward Voltage



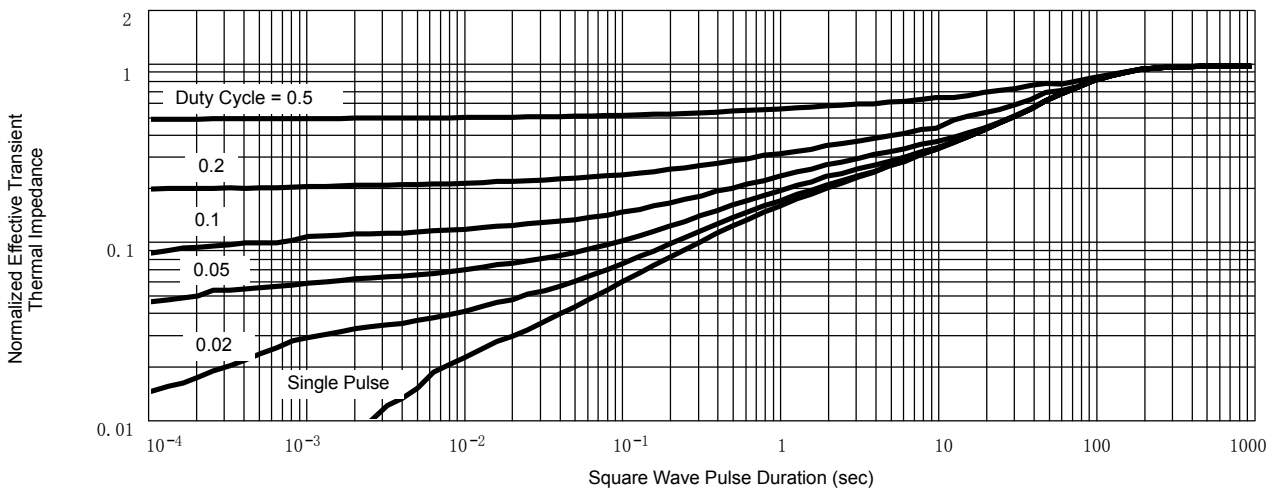
Maximum Avalanche and Drain Current vs. Ambient Temperature



Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



■ Typical Characteristics

